

English

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Product Change Notification - JAON-20ZDKM576 [\(Printer Friendly\)](#)

Date: 27 Nov 2015

Notification subject: CCB 1803 Initial Notice: Qualification of Ag ring plated lead-frame for selected products available in 20L SOIC package at NSEB assembly site.

Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of Ag ring plated lead-frame for selected products available in 20L SOIC package at NSEB assembly site.

Pre Change:
Using spot Ag plated lead-frame

Post Change:
Using Ag ring plated lead-frame.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB assembly site	NSEB assembly site
Wire material	Au wire	Au wire
Die attach material	8200T	8200T
Molding compound material	G605L	G605L
Lead frame material	C194	C194
Lead frame surface	spot Ag plated	Ag ring plated

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability by qualifying Ag ring plated lead-frame.

Change Implementation Status:
In Progress

Estimated First Ship Date:
March 15, 2016 (date code: 1611)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	November 2015				December 2015	January 2016	February 2016				March 2016				
	WW	45	46	47			48	05	06	07	08	09	10	11	12
Initial PCN Issue Date				X											
Qual Report Availability							X								
Final PCN Issue Date							X								
Implementation Date												X			

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

November 27, 2015: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

Spot Ag vs Ring Ag Plating Comparison.pdf
PCN_JAON-20ZDKM576_Qual_Plan.pdf
PCN_JAON-20ZDKM576_Affected_CPN.pdf
PCN_JAON-20ZDKM576_Affected_CPN.xls

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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